



Am27C400

4 Megabit (524,288 x 8-Bit/262,144 x 16-Bit)
ROM Compatible CMOS EPROM

DISTINCTIVE CHARACTERISTICS

- **Fast access time**
 - 100 ns
- **Low power consumption**
 - 100 μ A maximum CMOS standby current
- **Industry standard pinout:**
 - ROM compatible
 - 44-pin LCC, and PLCC packages provide easy upgrade to 8 Mbits, DIP upgrades require a 40- to 42-pin conversion
- **Single +5 V power supply**
- **$\pm 10\%$ power supply tolerance standard on most speeds**
- **100% Flashrite programming**
 - Typical programming time of 32 seconds
- **Latch-up protected to 100 mA from -1 V to $V_{CC} + 1$ V**
- **High noise immunity**

GENERAL DESCRIPTION

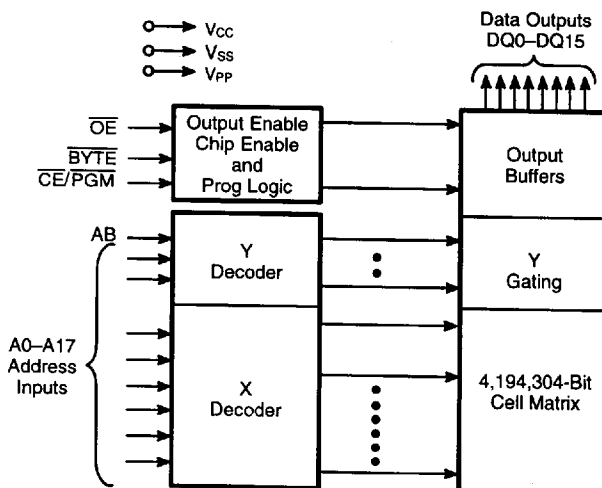
The Am27C400 is a 4 Mbit ultraviolet erasable programmable read-only memory that is functionally and pinout compatible with 4 Mbit masked ROMs. Under control of the $\overline{\text{BYTE}}$ input, the memory can be configured as either a 512K by 8-bit memory or a 256K by 16-bit memory. It operates from a single +5 V supply, has a static standby mode, and features fast single address location programming. Products are available in windowed ceramic packages as well as plastic one time programmable (OTP) packages for both through hole and surface mount applications.

Typically, any byte can be accessed in less than 100 ns, allowing operation with high-performance microprocessors without any WAIT states. The Am27C400 offers

separate Output Enable ($\overline{\text{OE}}$) and Chip Enable ($\overline{\text{CE}}$) controls, thus eliminating bus contention in a multiple bus microprocessor system.

AMD's CMOS process technology provides high speed, low power, and high noise immunity. Typical power consumption is only 150 mW in active mode, and 100 μ W in standby mode.

All signals are TTL levels, including programming signals. Bit locations may be programmed singly, in blocks, or at random. The Am27C400 supports AMD's Flashrite programming algorithm (100 μ s pulses) resulting in typical programming times of 32 seconds.



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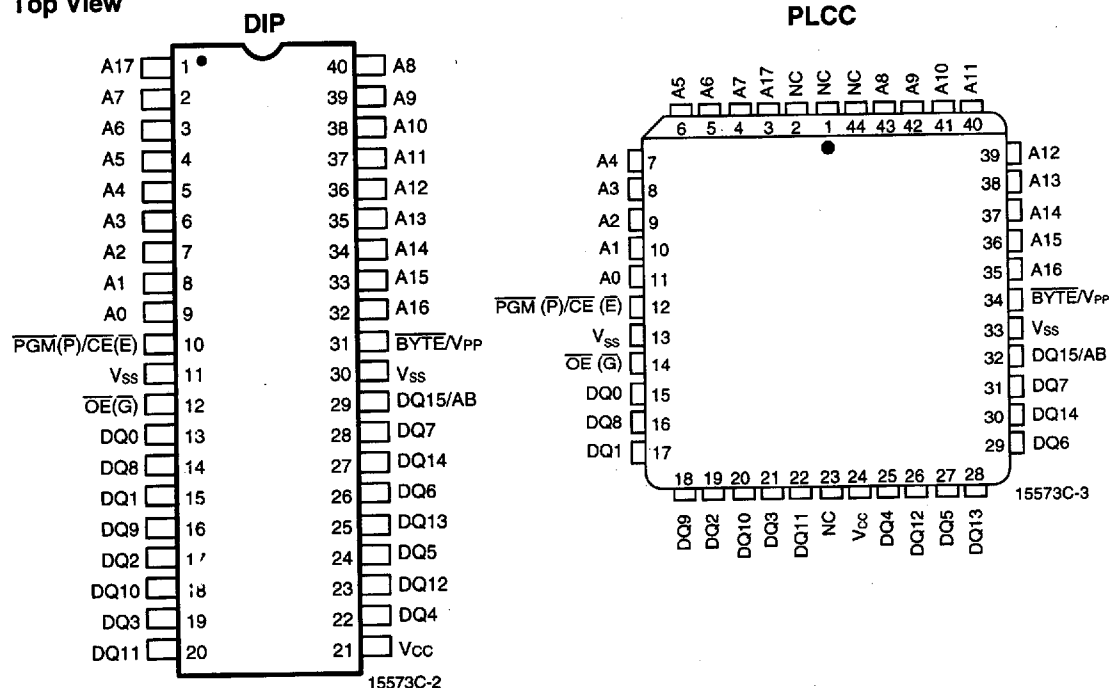


PRODUCT SELECTOR GUIDE

Family Part No.	Am27C400				
Ordering Part No:					
$V_{CC} \pm 5\%$	-105	-125			-255
$V_{CC} \pm 10\%$	-100	-120	-150	-200	
Max Access Time (ns)	100	120	150	200	250
\overline{CE} (E) Access Time (ns)	100	120	150	200	250
\overline{OE} (G) Access Time (ns)	50	50	65	75	100

CONNECTION DIAGRAM

Top View



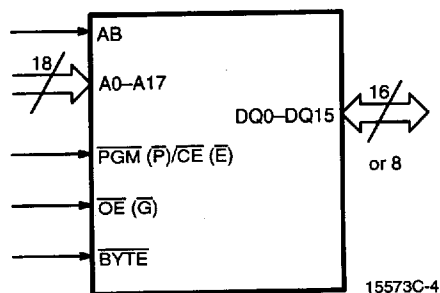
Notes:

1. Inner ring of numbers correspond to the package pins
2. JEDEC nomenclature is in parenthesis

PIN DESIGNATIONS

AB	= Address Input (BYTE Mode)
A0-A17	= Address Inputs
BYTE	= Byte/Word Switch
\overline{CE} (E)/PGM (\overline{P})	= Chip Enable and Program Enable Inputs
DQ0-DQ15	= Data Inputs/Outputs
NC	= No Internal Connection
\overline{OE} (G)	= Output Enable Input
V _{CC}	= V _{CC} Supply Voltage
V _{PP}	= Program Voltage Input
V _{SS}	= Ground

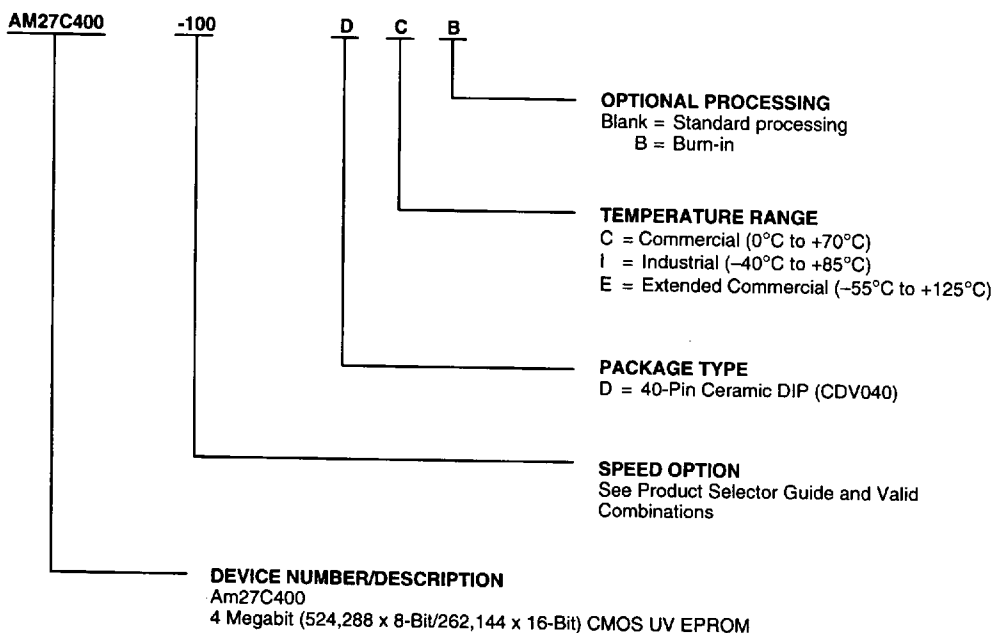
LOGIC SYMBOL



ORDERING INFORMATION

UV EPROM Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



Valid Combinations	
AM27C400-100	DC, DCB, DI, DIB
AM27C400-105	
AM27C400-120	DC, DCB, DI, DIB, DE, DEB
AM27C400-125	
AM27C400-150	
AM27C400-200	
AM27C400-255	DC, DCB, DI, DIB

Valid Combinations

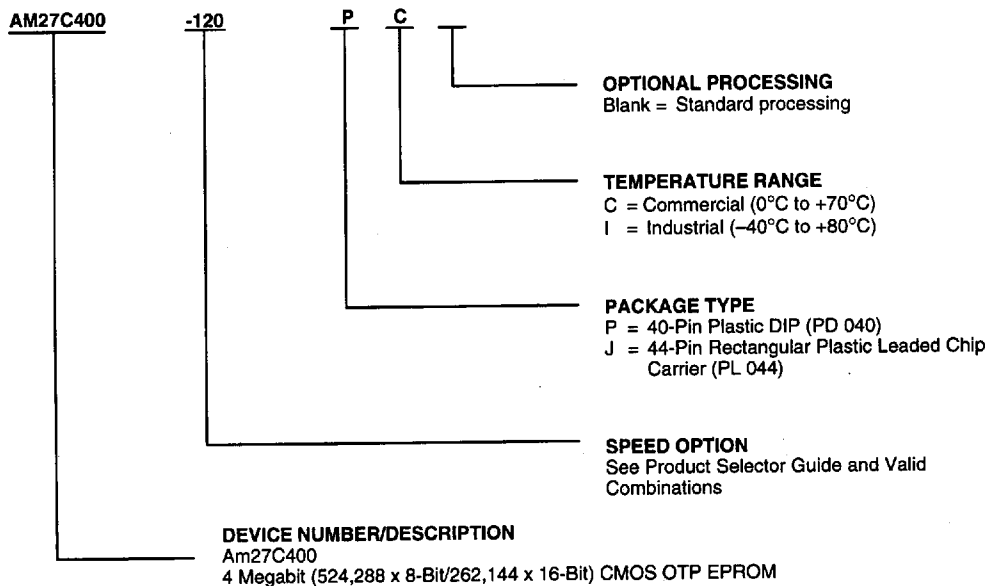
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.



ORDERING INFORMATION

OTP Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:



Valid Combinations	
AM27C400-120	PC, JC, PI, JI
AM27C400-125	
AM27C400-150	
AM27C400-200	
AM27C400-255	

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations and to check on newly released combinations.

Group A Tests

Group A tests consist of Subgroups
1, 2, 3, 7, 8, 9, 10, 11.

FUNCTIONAL DESCRIPTION

Erasing the Am27C400

In order to clear all locations of their programmed contents, it is necessary to expose the Am27C400 to an ultraviolet light source. A dosage of 15 W seconds/cm² is required to completely erase an Am27C400. This dosage can be obtained by exposure to an ultraviolet lamp — wavelength of 2,537 Å—with intensity of 12,000 μW/cm² for 15 to 20 minutes. The Am27C400 should be directly under and about one inch from the source and all filters should be removed from the UV light source prior to erasure.

It is important to note that the Am27C400 and similar devices will erase with light sources having wavelengths shorter than 4000 Å. Although erasure times will be much longer than with UV sources at 2,537 Å, exposure to fluorescent light and sunlight will eventually erase the Am27C400 and exposure to them should be prevented to realize maximum system reliability. If used in such an environment, the package window should be covered by an opaque label or substance.

Programming the Am27C400

Upon delivery or after each erasure the Am27C400 has all 4,194,304 bits in the "ONE" or HIGH state. "ZEROS" are loaded into the Am27C400 through the procedure of programming.

The programming mode is entered when 12.75 ± 0.25 V is applied to the V_{PP} pin, $\overline{CE/PGM}$ is at V_{IL} , and \overline{OE} is at V_{IH} .

For programming, the data to be programmed is applied 16 bits in parallel to the data output pins.

The Flashrite algorithm reduces programming time by using 100 μs programming pulses and by giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data does not verify, additional pulses are given until it verifies or the maximum is reached. This process is repeated while sequencing through each address of the Am27C400. This part of the algorithm is done at $V_{CC} = 6.25$ V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. After the final address is completed, the entire EPROM memory is verified at $V_{CC} = V_{PP} = 5.25$ V.

Please refer to Section 6.0 for programming and flow chart characteristics.

Program Inhibit

Programming of multiple Am27C400s in parallel with different data is also easily accomplished. Except for $\overline{CE/PGM}$, all like inputs of the parallel Am27C400 may be common. A TTL low-level program pulse applied to

an Am27C400 $\overline{CE/PGM}$ input with $V_{PP} = 12.75 \text{ V} \pm 0.25 \text{ V}$, and \overline{OE} HIGH will program that Am27C400. A high-level $\overline{CE/PGM}$ input inhibits the other Am27C400 devices from being programmed.

Program Verify

A verify should be performed on the programmed bits to determine that they were correctly programmed. The verify should be performed with \overline{OE} at V_{IL} , $\overline{CE/PGM}$ at V_{IH} and V_{PP} between 12.5 V and 13.0 V.

Auto Select Mode

The auto select mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional in the $25^\circ\text{C} \pm 5^\circ\text{C}$ ambient temperature range that is required when programming the Am27C400.

To activate this mode, the programming equipment must force $12.0 \text{ V} \pm 0.5 \text{ V}$ on address line A9 of the Am27C400. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from V_{IL} to V_{IH} . All other address lines must be held at V_{IL} during auto select mode.

Byte 0 ($A_0 = V_{IL}$) represents the manufacturer code, and Byte 1 ($A_0 = V_{IH}$), the device identifier code. For the Am27C400, these two identifier bytes are given in the Mode Select table. All identifiers for manufacturer and device codes will possess odd parity, with the MSB (DQ7) defined as the parity bit.

Read Mode

The Am27C400 has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip Enable ($\overline{CE/PGM}$) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to the delay from $\overline{CE/PGM}$ to output (t_{CE}). Data is available at the outputs t_{OE} after the falling edge of \overline{OE} , assuming that $\overline{CE/PGM}$ has been LOW and addresses have been stable for at least $t_{ACC} - t_{OE}$.

Byte Mode

The user has the option of reading data in either 16-bit words or 8-bit bytes under control of the \overline{BYTE} input. With the \overline{BYTE} input HIGH, inputs A0–A17 will address 256K words of 16-bit data. When the \overline{BYTE} input is LOW, AB functions as the least significant address input and 512K bytes of data can be accessed. The 8 bits of data will appear on DQ0–DQ7.

Standby Mode

The Am27C400 has a CMOS standby mode which reduces the maximum V_{CC} current to 100 μ A. It is placed in CMOS-standby when $\overline{CE}/\overline{PGM}$ is at $V_{CC} \pm 0.3$ V. The Am27C400 also has a TTL-standby mode which reduces the maximum V_{CC} current to 1.0 mA. It is placed in TTL-standby when $\overline{CE}/\overline{PGM}$ is at V_{IH} . When in standby mode, the outputs are in a high-impedance state, independent of the \overline{OE} input.

Output OR-Tieing

To accommodate multiple memory connections, a two-line control function is provided to allow for:

- Low memory power dissipation
- Assurance that output bus contention will not occur

It is recommended that $\overline{CE}/\overline{PGM}$ be decoded and used as the primary device-selecting function, while \overline{OE} be made a common connection to all devices in the array and connected to the READ line from the system control

bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

System Applications

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a 0.1 μ F ceramic capacitor (high frequency, low inherent inductance) should be used on each device between V_{CC} and V_{SS} to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a 4.7 μ F bulk electrolytic capacitor should be used between V_{CC} and V_{SS} for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

MODE SELECT TABLE

Mode	Pins	$\overline{CE}/\overline{PGM}$	\overline{OE}	A0	A9	V_{PP}	Outputs
Read		V_{IL}	V_{IL}	X	X	X	DOUT
Output Disable		V_{IL}	V_{IH}	X	X	X	Hi-Z
Standby (TTL)		V_{IH}	X	X	X	X	Hi-Z
Standby (CMOS)		$V_{CC} \pm 0.3$ V	X	X	X	X	Hi-Z
Program		V_{IL}	V_{IH}	X	X	V_{PP}	DIN
Program Verify		V_{IH}	V_{IL}	X	X	V_{PP}	DOUT
Program Inhibit		V_{IH}	V_{IH}	X	X	V_{PP}	Hi-Z
Auto Select (Note 3)	Manufacturer Code	V_{IL}	V_{IL}	V_{IL}	V_{H}	X	01H
	Device Code	V_{IL}	V_{IL}	V_{IH}	V_{H}	X	9DH

Notes:

1. $V_{H} = 12.0$ V \pm 0.5 V
2. X = Either V_{IH} or V_{IL}
3. A1-A8 = A0-A17 = V_{IL}
4. See DC Programming Characteristics for V_{PP} voltage during programming.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature	
OTP Products	−65°C to +125°C
All Other Products	−65°C to +150°C
Ambient Temperature	
with Power Applied	−55°C to +125°C
Voltage with Respect To V_{SS}	
All pins except A9, V_{PP} , V_{CC}	−0.6 V to $V_{CC} + 0.6$ V
A9 and V_{PP}	−0.6 V to +13.5 V
V_{CC}	−0.6 V to +7.0 V

Notes:

1. Minimum DC voltage on input or I/O pins is −0.5 V. During transitions, the inputs may overshoot V_{SS} to −2.0 V for periods of up to 20 ns. Maximum DC voltage on input and I/O pins is $V_{CC} + 0.5$ V which may overshoot to $V_{CC} + 2.0$ V for periods up to 20 ns.
2. For A9 and V_{PP} the minimum DC input is −0.5 V. During transitions, A9 and V_{PP} may overshoot V_{SS} to −2.0 V for periods of up to 20 ns. A9 and V_{PP} must not exceed 13.5 V for any period of time.

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure of the device to absolute maximum rating conditions for extended periods may affect device reliability.

OPERATING RANGES**Commercial (C) Devices**

Ambient Temperature (T_A) 0°C to +70°C

Industrial (I) Devices

Ambient Temperature (T_A) −40°C to +85°C

Extended Commercial (E) Devices

Ambient Temperature (T_A) −55°C to +125°C

Supply Read Voltages

V_{CC} for Am27C400-XX5 +4.75 V to +5.25 V

V_{CC} for Am27C400-XX0 +4.50 V to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range unless otherwise specified. (Notes 1, 2, 3 and 4)

Parameter Symbol	Parameter Description	Test Conditions	Min	Max	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -400 μ A	2.4		V
V _{OL}	Output LOW Voltage	I _{OL} = 2.1 mA		0.45	V
V _{IH}	Input HIGH Voltage		2.0	V _{CC} + 0.5	V
V _{IL}	Input LOW Voltage		-0.5	+0.8	V
I _{LI}	Input Load Current	V _{IN} = 0 V to +V _{CC}		1.0	μ A
I _{LO}	Output Leakage Current	V _{OUT} = 0 V to +V _{CC}		5.0	μ A
I _{CC1}	V _{CC} Active Current (Note 3)	\overline{CE} = V _{IL} , f = 5 MHz, I _{OUT} = 0 mA	C/I Devices	40	mA
			E Devices	60	
I _{CC2}	V _{CC} TTL Standby Current	\overline{CE} = V _{IH}		1.0	mA
I _{CC3}	V _{CC} CMOS Standby Current	\overline{CE} = V _{CC} \pm 0.3 V		100	μ A
I _{PP1}	V _{PP} Current During Read	\overline{CE} = \overline{OE} = V _{IL} , V _{PP} = V _{CC}		100	μ A

Notes:

1. V_{CC} must be applied simultaneously or before V_{PP}, and removed simultaneously or after V_{PP}.
2. **Caution:** The Am27C400 must not be removed from (or inserted into) a socket when V_{CC} or V_{PP} is applied.
3. I_{CC1} is tested with \overline{OE}/V_{PP} = V_{IH} to simulate open outputs.
4. Minimum DC Input Voltage is -0.5 V. During transitions, the inputs may overshoot to -2.0 V for periods less than 20 ns. Maximum DC Voltage on output pins is V_{CC} + 0.5 V, which may overshoot to V_{CC} + 2.0 V for periods less than 20 ns.

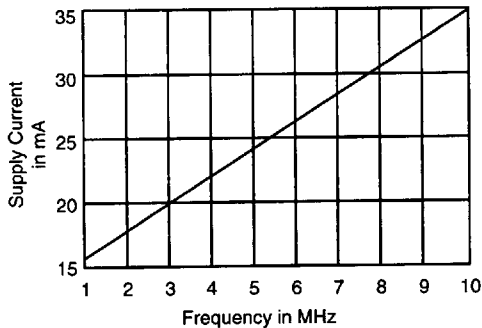


Figure 1. Typical Supply Current vs. Frequency
V_{CC} = 5.5 V, T = 25°C

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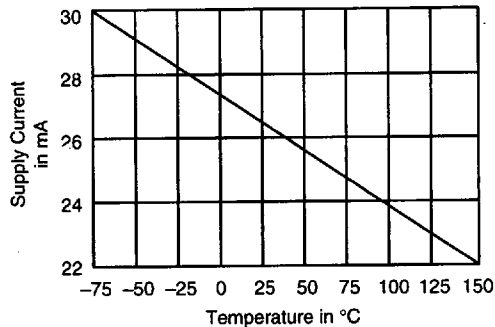


Figure 2. Typical Supply Current vs. Temperature
V_{CC} = 5.5 V, f = 5 MHz

15573C-6

CAPACITANCE

Parameter Symbol	Parameter Description	Test Conditions	CDV040		PD 040		PL 044		Unit
			Typ	Max	Typ	Max	Typ	Max	
C _{IN}	Input Capacitance	V _{IN} = 0	9	12	6	8	9	11	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0	12	15	9	11	13	15	pF

Notes:

1. This parameter is only sampled and not 100% tested.
2. T_A = +25°C, f = 1 MHz.

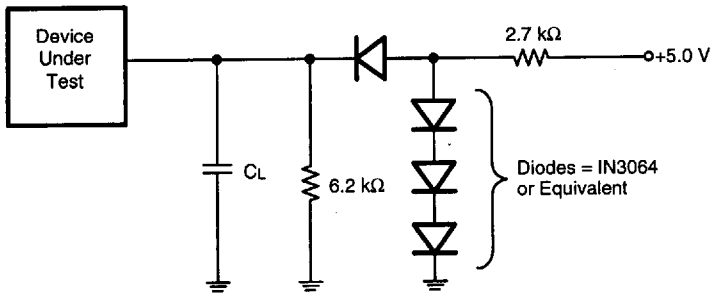
SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Notes 1, 3 and 4)

Parameter Symbols		Parameter Description	Test Conditions	Am27C400					Unit
JEDEC	Standard			-105 -100	-125 -120	-150	-200	-255	
t _{AVQV}	t _{ACC}	Address to Output Delay	$\overline{CE} = \overline{OE} = V_{IL}$	Min	—	—	—	—	
				Max	100	120	150	200	250 ns
t _{ELQV}	t _{CE}	Chip Enable to Output Delay	$\overline{OE} = V_{IL}$	Min	—	—	—	—	
				Max	100	120	150	200	250 ns
t _{GLQV}	t _{OE}	Output Enable to Output Delay	$\overline{CE} = V_{IL}$	Min	—	—	—	—	
				Max	50	50	55	60	75 ns
t _{EHQZ} , t _{GHQZ}	t _{DF} (Note 2)	Chip Enable HIGH or Output Enable HIGH, whichever comes first, to Output Float		Min	—	—	—	—	
				Max	30	30	30	40	60 ns
t _{AXQX}	t _{OH}	Output Hold from Addresses, \overline{CE} , or \overline{OE} , whichever occurred first		Min	0	0	0	0	
				Max	—	—	—	—	ns

Notes:

1. V_{CC} must be applied simultaneously or before V_{PP}, and removed simultaneously or after V_{PP}.
2. This parameter is only sampled and not 100% tested.
3. **Caution:** The Am27C400 must not be removed from (or inserted into) a socket or board when V_{PP} or V_{CC} is applied.
4. Output Load: 1 TTL gate and C_L = 100 pF
 Input Rise and Fall Times: 20 ns
 Input Pulse Levels: 0.45 V to 2.4 V
 Timing Measurement Reference Level: 0.8 V and 2 V for inputs and outputs.

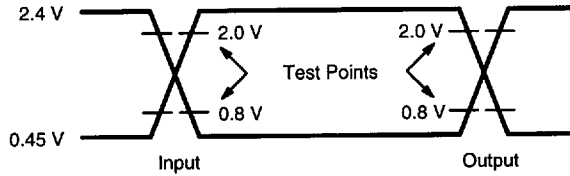
SWITCHING TEST CIRCUIT



15573C-7

$C_L = 100$ pF including jig capacitance


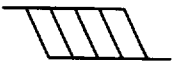

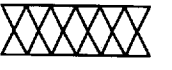
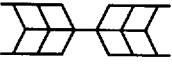
SWITCHING TEST WAVEFORM



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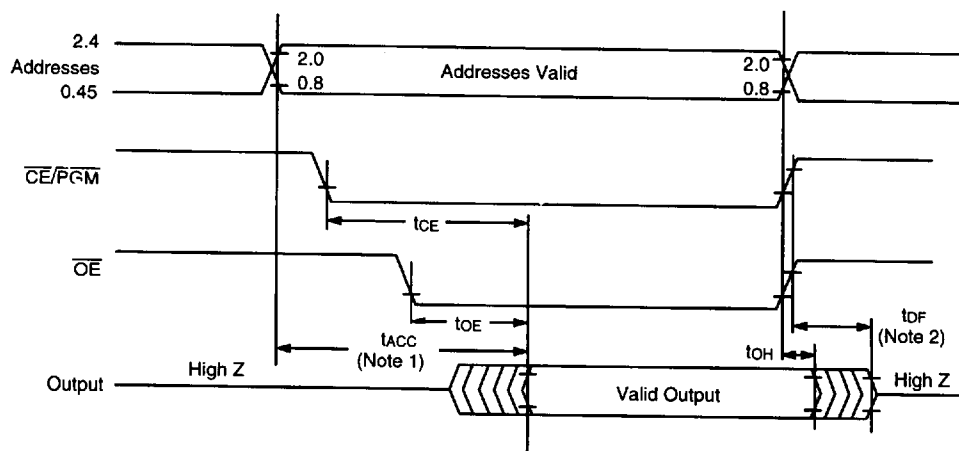
AC Testing: Inputs are driven at 2.4 V for a logic "1" and 0.45 for a logic "0". Input pulse rise and fall times are ≤ 20 ns.

KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	Must Be Steady	Will Be Steady
	May Change from H to L	Will Be Changing from H to L
	May Change from L to H	Will Be Changing from L to H
	Don't Care, Any Change Permitted	Changing, State Unknown
	Does Not Apply	Center Line is High Impedance "Off" State

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SWITCHING WAVEFORMS



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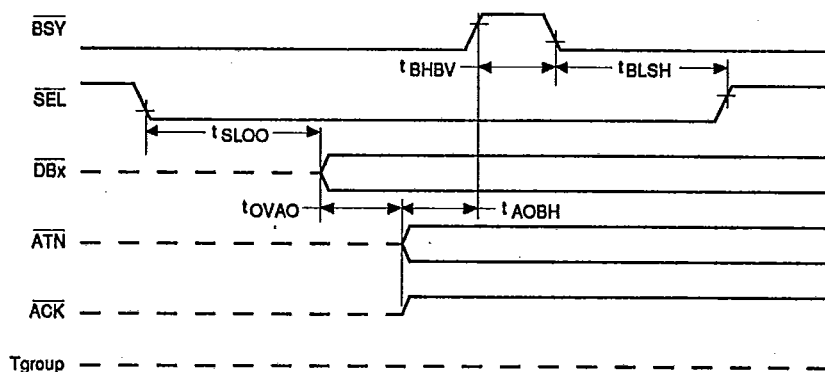
Notes:

- \overline{OE} may be delayed up to $t_{ACC} - t_{OE}$ after the falling edge of the addresses without impact on t_{ACC} .
- t_{DF} is specified from \overline{OE} or \overline{CE} , whichever occurs first.

SELECTING A TARGET (AS AN INITIATOR)

T-52-33-27

Symbol	Characteristic	Min	Max	Units
t_{SLOO}	SEL Out Low to "OR-ED" ID Out	1.2		us
t_{OVAO}	"OR-ED" ID Out Valid to ACK, ATN Out	100		ns
t_{AOBH}	ACK, ATN Out Valid to BSY Out High	100		ns
t_{BHBV}	BSY Out High to BSY In Low, Valid	400		ns
t_{BLSH}	BSY In Low to SEL Out High	100		ns

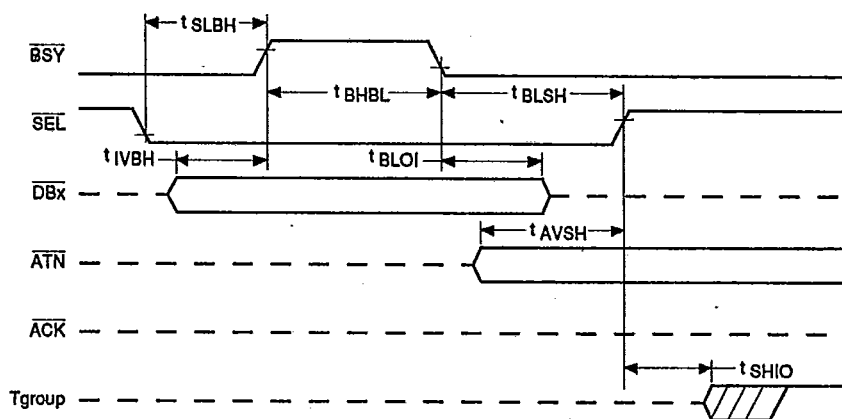


NOTE: Tgroup = signals driven by a Target = $\overline{I/O}$, $\overline{C/D}$, \overline{MSG} , \overline{REQ}

11853-027A

RESPONSE TO SELECTION (AS A TARGET)

Symbol	Characteristic	Min	Max	Units
t_{SLBH}	SEL In Low to \overline{BSY} In High			ns
t_{IVBH}	"OR-ED" ID Valid In to \overline{BSY} In High	0		ns
t_{BHBL}	SEL Low, ID Valid, \overline{BSY} High to \overline{BSY} Low	0.4	200	us
t_{BLOI}	BSY Out Low to "OR-ED" ID Invalid In	0		ns
t_{BLSH}	BSY Out Low to SEL In High	0		ns
t_{AVSH}	ATN Valid In to SEL In High	0		ns
t_{SHIO}	SEL In High to Tgroup Out	100		ns



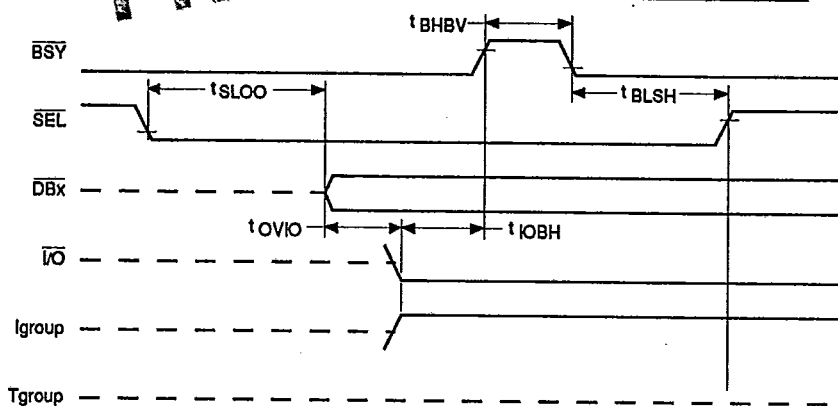
NOTE: Tgroup = signals driven by a Target = $\overline{I/O}$, $\overline{C/D}$, \overline{MSG} , \overline{REQ}

11853-028A

RESELECTING AN INITIATOR (AS A TARGET)

T-52-33-27

Symbol	Characteristic	Min	Max	Units
t_{SLOO}	SEL Out Low to "OR-ED" ID Out	2		μs
t_{OVIO}	"OR-ED" ID Out Valid to I/O & Tgroup Out Valid	100		ns
t_{IOBH}	I/O & Tgroup Out Valid to BSY Out High	100		ns
t_{BHBV}	BSY Out High to BSY In Low Valid	400		ns
t_{BLSH}	BSY In Low to SEL Out High	100		ns

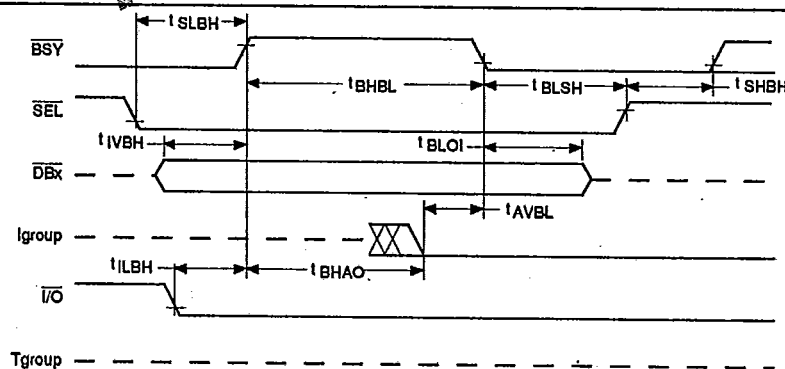


NOTE: Tgroup = signals driven by a Target = $\overline{C/D}$, MSG, REQ
 Igroup = signals driven by an Initiator = ATN, ACK

11853-028A

RESPONSE TO RESELECTION (AS AN INITIATOR)

Symbol	Characteristic	Min	Max	Units
t_{SLBH}	SEL In Low to BSY In High	0		ns
t_{IVBH}	"OR-ED" ID Valid In to BSY In High	0		ns
t_{ILBH}	I/O In Low to BSY In High	0		ns
t_{BHAO}	SEL Low, ID Valid, BSY High to Igroup Out	100		ns
t_{AVBL}	Igroup Valid Out to BSY Out Low	100		ns
t_{BHBL}	BSY In High to BSY Out Low	0.4	200	μs
t_{BLOI}	BSY Out Low to "OR-ED" ID Invalid In	0		ns
t_{BLSH}	BSY Out Low to SEL In High	0		ns
t_{SHBH}	SEL In High to BSY Out High	0		ns



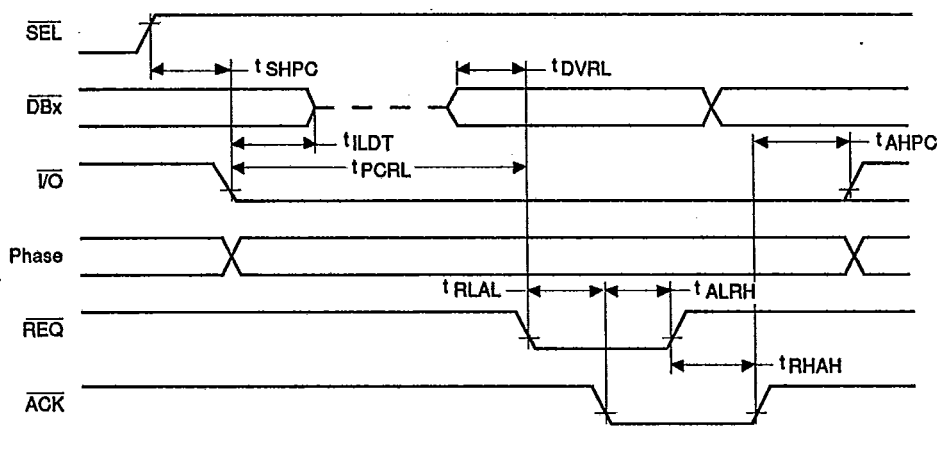
Tgroup = signals driven by a Target = $\overline{C/D}$, MSG, REQ
 Igroup = signals driven by an Initiator = ATN, ACK
 *** BSY will still be driven by the reselecting target.

11853-030A

RECEIVE ASYNCHRONOUS INFORMATION TRANSFER IN (ACTING AS AN INITIATOR)

T-52-33-27

Symbol	Characteristic	Min	Max	Units
t_{SHPC}	\overline{SEL} In High to Phase Change In	0		ns
$t_{ILD T}$	$\overline{I/O}$ In Low to Data Bus TRISTATE	0	125	ns
t_{PCRL}	Phase Change In to \overline{REQ} In Low	400		ns
t_{DVRL}	Data Valid In to \overline{REQ} In Low	0		ns
t_{RLAL}	\overline{REQ} In Low to \overline{ACK} Out Low	0	175	ns
t_{ALDI}	\overline{ACK} Out Low to Data Invalid In	0		ns
t_{ALRH}	\overline{ACK} Out Low to \overline{REQ} In High	0		ns
t_{RHAH}	\overline{REQ} In High to \overline{ACK} Out High	0	175	ns
t_{AHPC}	\overline{ACK} Out High to Phase Change In	0		ns



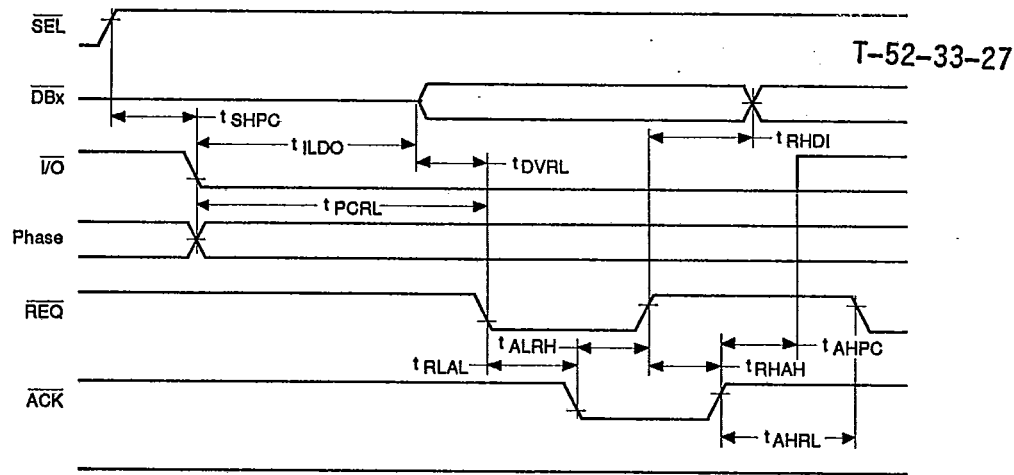
ATN

NOTE: Phase = signals that define the bus phase $\overline{C/D}$, MSG

11853-031A

SEND ASYNCHRONOUS INFORMATION TRANSFER IN (ACTING AS A TARGET)

Symbol	Characteristic	Min	Max	Units
t_{SHPC}	\overline{SEL} In High to Phase Change Out	100		ns
t_{ILDO}	$\overline{I/O}$ Out Low to Data Out	800		ns
t_{DVRL}	Data Out Valid to \overline{REQ} Out Low	55		ns
t_{PCRL}	Phase Change Out to \overline{REQ} Out Low	500		ns
t_{RLAL}	\overline{REQ} Out Low to \overline{ACK} In Low	0		ns
t_{ALRH}	\overline{ACK} In Low to \overline{REQ} Out High	0	175	ns
t_{ALDI}	\overline{ACK} In Low to Data Out Invalid	0		ns
t_{RHAH}	\overline{REQ} Out High to \overline{ACK} In High	0		ns
t_{AHPC}	\overline{ACK} In High to Phase Change Out	100		ns
t_{AHRL}	\overline{ACK} In High to \overline{REQ} Out Low	0	175	ns

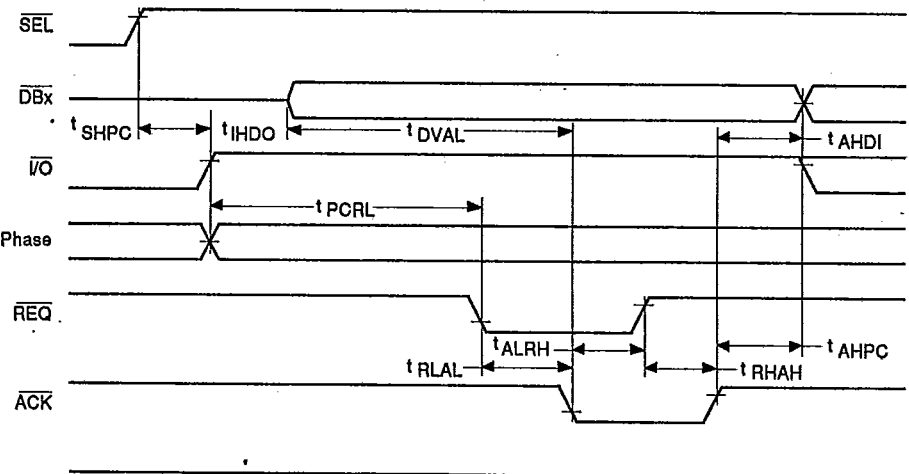


ATN NOTE: Phase = signals that define the bus phase $\overline{C/D}$, \overline{MSG}

11853-032A

SEND ASYNCHRONOUS INFORMATION TRANSFER OUT (ACTING AS AN INITIATOR)

Symbol	Characteristic	Min	Max	Units
t_{SHPC}	SEL In High to Phase Change In	0		ns
t_{IHDO}	I/O In High to Data Out	0		ns
t_{PCRL}	Phase Change In to REQ In Low	400		ns
t_{RLAL}	REQ In Low to ACK Out Low	0	175	ns
t_{DVAL}	Data Out Valid to ACK Out Low	55		ns
t_{ALRH}	ACK Out Low to REQ In High	0		ns
t_{RHAH}	REQ In High to ACK Out High	0	175	ns
t_{RHDI}	REQ In High to Data Out Invalid	0		ns
t_{AHPC}	ACK Out High to Phase Change In	0		ns



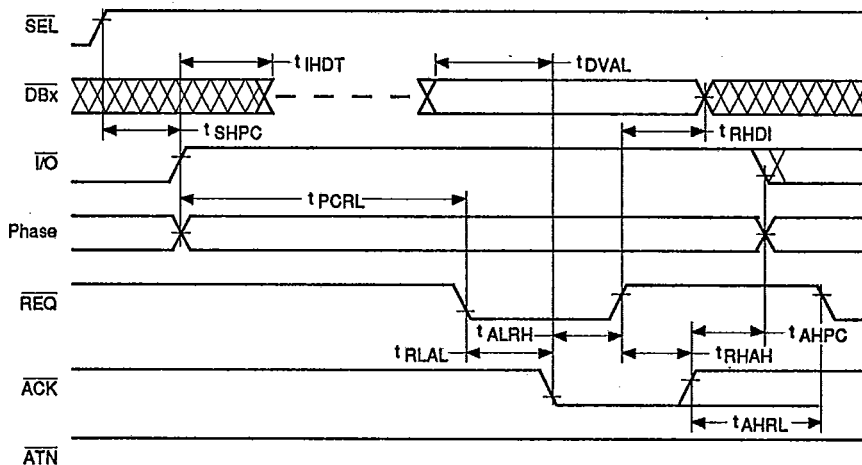
ATN NOTE: Phase = signals that define the bus phase $\overline{C/D}$, \overline{MSG}

11853-033A

RECEIVE ASYNCHRONOUS INFORMATION TRANSFER OUT (ACTING AS A TARGET)

Symbol	Characteristic	Min	Max	Units
t_{SHPC}	\overline{SEL} In High to Phase Change Out	100		ns
t_{IHDT}	$\overline{I/O}$ Out High to Data Bus TRISTATE	0		ns
t_{PCRL}	Phase Change to \overline{REQ} Out Low	500		ns
t_{RLAL}	\overline{REQ} Out Low to \overline{ACK} In Low	0		ns
t_{DVAL}	Data In Valid to \overline{ACK} In Low	0		ns
t_{ALRH}	\overline{ACK} In Low to \overline{REQ} Out High	0	175	ns
t_{RHDI}	\overline{REQ} Out High to Data In Invalid	0		ns
t_{RHAH}	\overline{REQ} Out High to \overline{ACK} In High	0		ns
t_{AHPC}	\overline{ACK} In High to Phase Change Out	0		ns
t_{AHRL}	\overline{ACK} In High to \overline{REQ} Out Low	0	175	ns

T-52-33-27

NOTE: Phase = signals that define the bus phase $\overline{C/D}$, \overline{MSG}

11853-034A

RECEIVE SYNCHRONOUS INFORMATION TRANSFER IN (ACTING AS AN INITIATOR)

Symbol	Characteristic	Min	Max	Units
t_{DVRL}	Data Valid In to \overline{REQ} In Low	0		ns
t_{RLDI}	\overline{REQ} In Low to DATA Invalid	45		ns
t_{RLRH}	\overline{REQ} In Low to \overline{REQ} In High	50		ns
t_{RHRL}	\overline{REQ} In High to \overline{REQ} In Low	50		ns
t_{ALAH}	\overline{ACK} Out Low to \overline{ACK} Out High	$T_{cyc}-10$		ns
t_{AHAL}	\overline{ACK} Out High to \overline{ACK} Out Low	$T_{cyc}-25$		ns
t_{AHPC}	\overline{ACK} Out High to Phase Change	0		ns

Parameters t_{SHPC} , t_{IHDT} , and t_{PCRL} are also applicable and are identical to those in Receive Asynchronous Information Transfer In (Acting as an Initiator), top of page 37.